BRIGHTEK

BRIGHTEK (EUROPE) LIMITED

Brighten Up The World With LED !

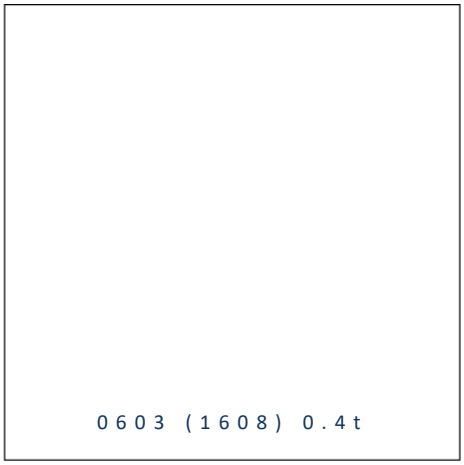
ISO/TS 16949:2009 BS EN ISO 14001:2004 QC 080000 IECQ HSPM

PRODUCT DATASHEET

- ▶ PCB / CHIP LED
- ▶ 0603 (1608) 0.4t
- ▶ Blue (465~475nm)

Release Date: 09 January 2025 Version: A1.0

N0B68S60-5MA



0603 (1608) 0.4t

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RoHS Compliant

FEATURES:

- **Package:** PCB / CHIP LED Top View
- **Forward Current:** 5mA
- **Forward Voltage (typ.):** 2.8V
- **Luminous Intensity (typ.):** 20mcd@5mA
- **Colour:** Blue
- **Dominant Wavelength:** 465~475nm
- **Viewing Angle:** 120°
- **Materials:**
  - Die: InGaN
  - Resin: Epoxy (Water Clear)
- **Operating Temperature:** -40~+85°C
- **Storage Temperature:** -40~+90°C
- **Grouping Parameters:**
  - Forward voltage
  - Luminous intensity
  - Dominant wavelength
- **Soldering Methods:** Reflow
- **MSL Level:** 3 acc. to JEDEC
- **Packing:** 8mm tape with max.4000/reel, ø180mm (7'')

APPLICATIONS:

- Backlighting
- Indication Light
- Switch light
- Dashboard

CHARACTERISTICS:

Absolute Maximum Characteristics (T_a=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I_F	10	mA
Peak Forward Current (duty 1/10; 1kHz)	I_{FP}	40	mA
Power Dissipation	P_D	40	mW
Electrostatic Discharge (HBM)	ESD	2000	V
Operating Temperature	T_{OPR}	-40~+85	°C
Storage Temperature	T_{STG}	-40~+90	°C

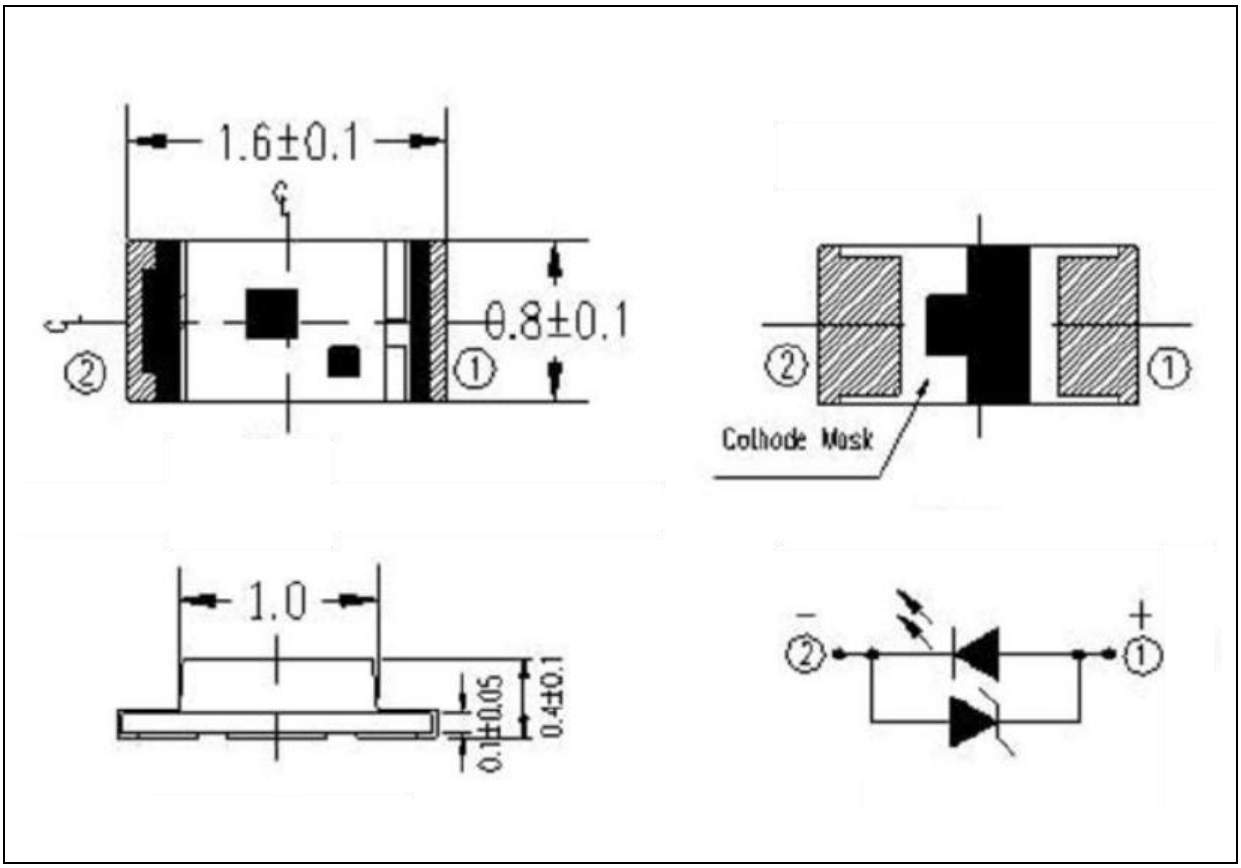
Electrical & Optical Characteristics (T_a=25°C)

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Forward Voltage	V_F	2.5	---	3.1	V	I_F=5mA
Luminous Intensity	I_V	11.5	---	28.5	mcd	I_F=5mA
Dominant Wavelength	λ_D	465	---	475	nm	I_F=5mA
Peak Wavelength	λ_P	---	468	---	nm	I_F=5mA
Spectrum Radiation Bandwidth	$\Delta\lambda$	---	25	---	nm	I_F=5mA
Viewing Angle	$2\theta_{1/2}$	---	120	---	deg	I_F=5mA

1. Luminous intensity (I_V) ±10%, Forward Voltage (V_F) ±0.1V.

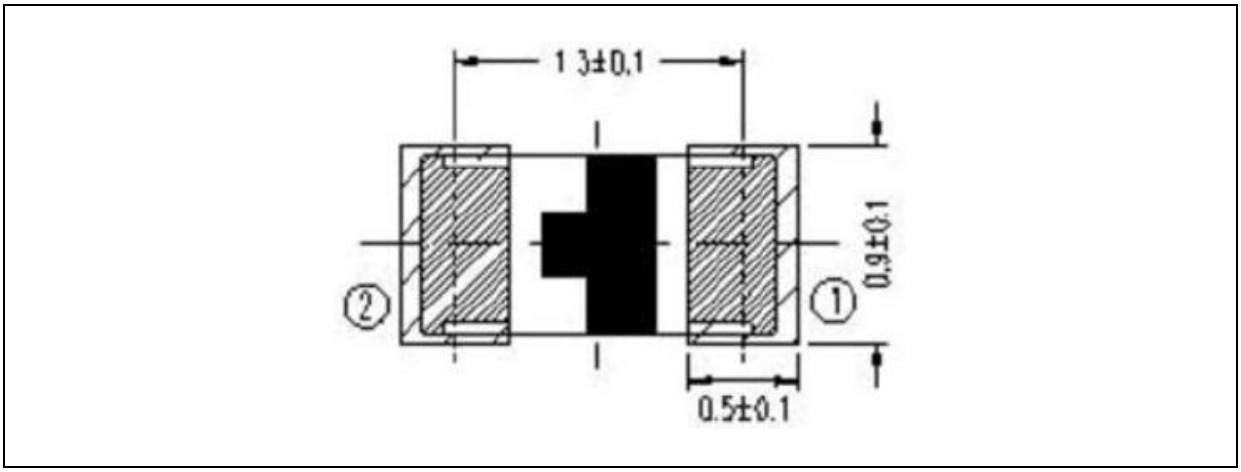
OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).
2. Tolerance ±0.2mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



1. Dimensions are in millimetre (mm).
2. Tolerance ±0.1mm with angle tolerance ±0.5°.

BINNING GROUPS:

Forward Voltage Classifications (I_F = 5mA):

Code	Min.	Max.	Unit
9	2.5	2.7	V
10	2.7	2.9	
11	2.9	3.0	

Luminous Intensity Classifications (I_F = 5mA):

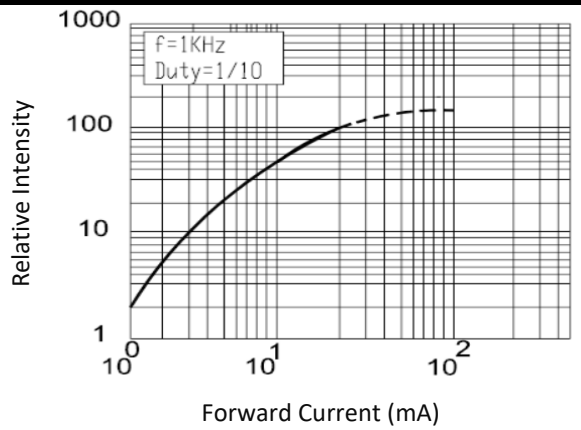
Code	Min.	Max.	Unit
L1	11.5	14.5	mcd
L2	14.5	18.0	
M1	18.0	22.5	
M2	22.5	28.5	

Dominant Wavelength Classifications (I_F = 5mA):

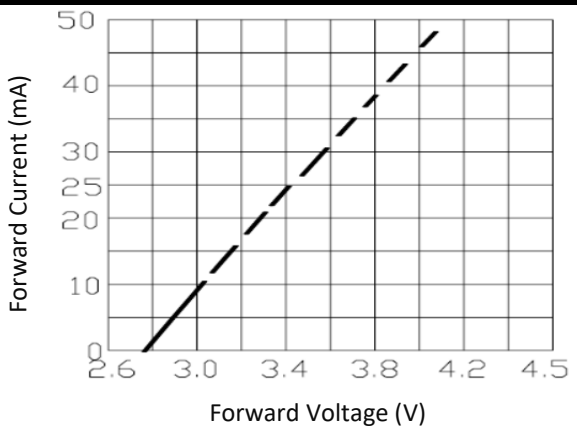
Code	Min.	Max.	Unit
X	465	470	nm
Y	470	475	

ELECTRO-OPTICAL CHARACTERISTICS:

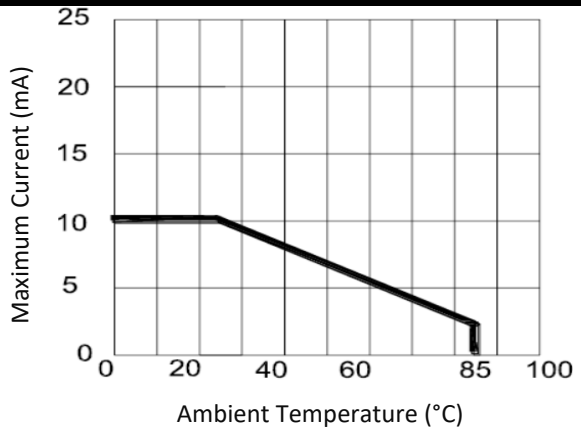
Relative Intensity v.s. Forward Current



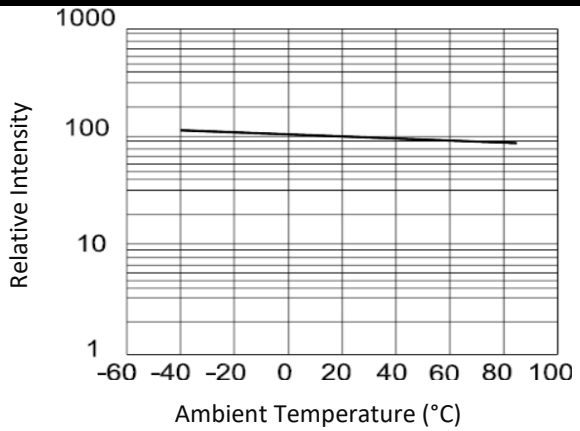
Forward Current v.s. Forward Voltage



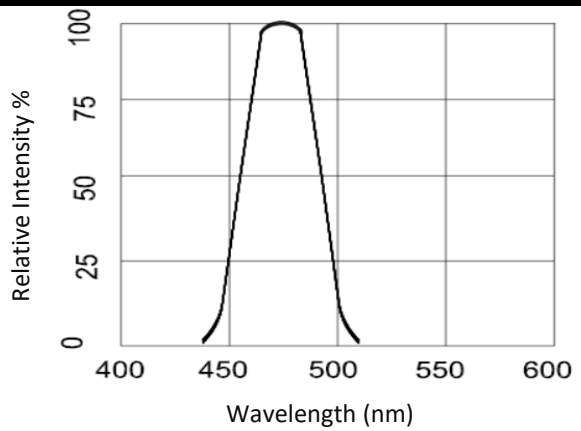
Temperature Derating Chart



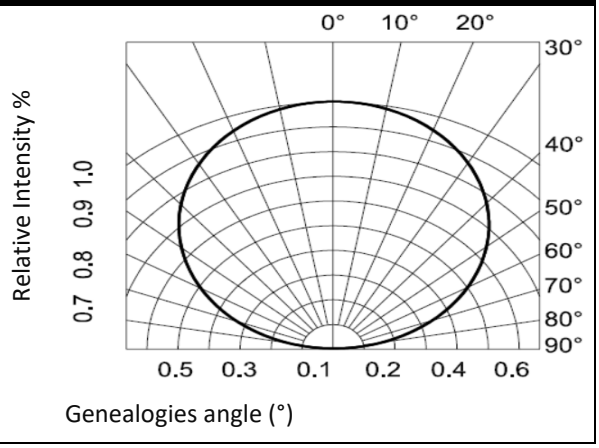
Relative Intensity Flux v.s. Junction Temperature



Relative Intensity v.s. Wavelength

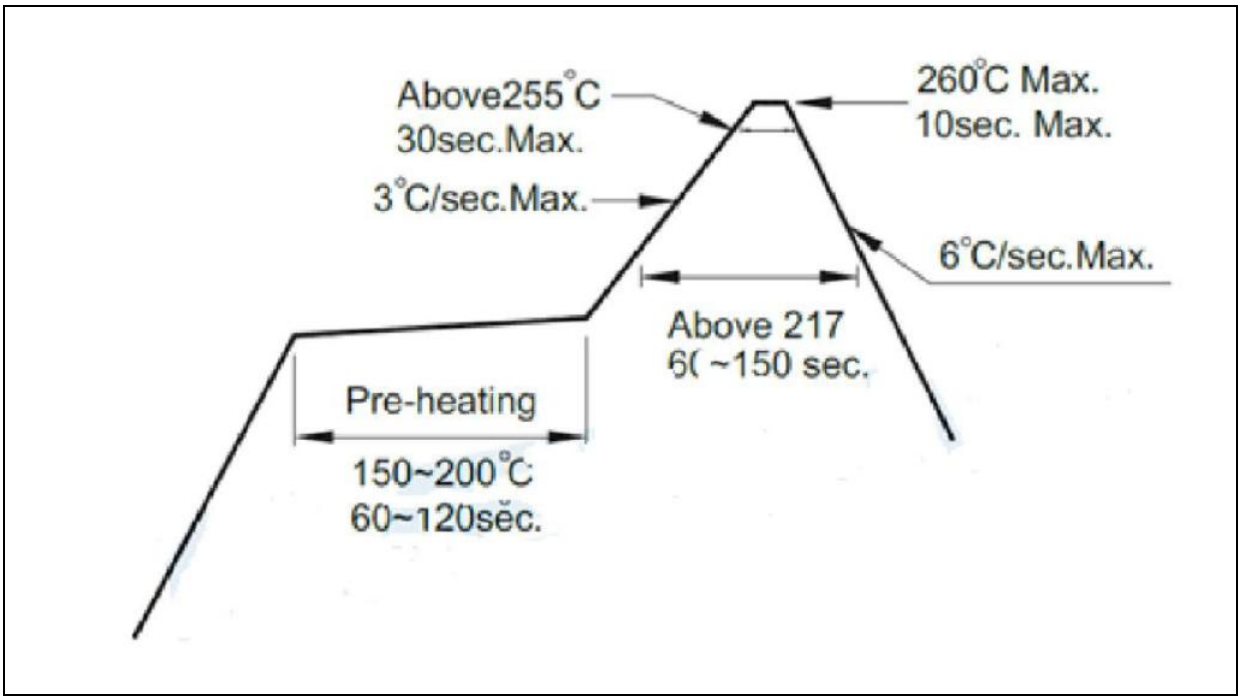


Relative Intensity v.s. Angular Displacement



RECOMMENDED SOLDERING PROFILE:

Reflow solder:



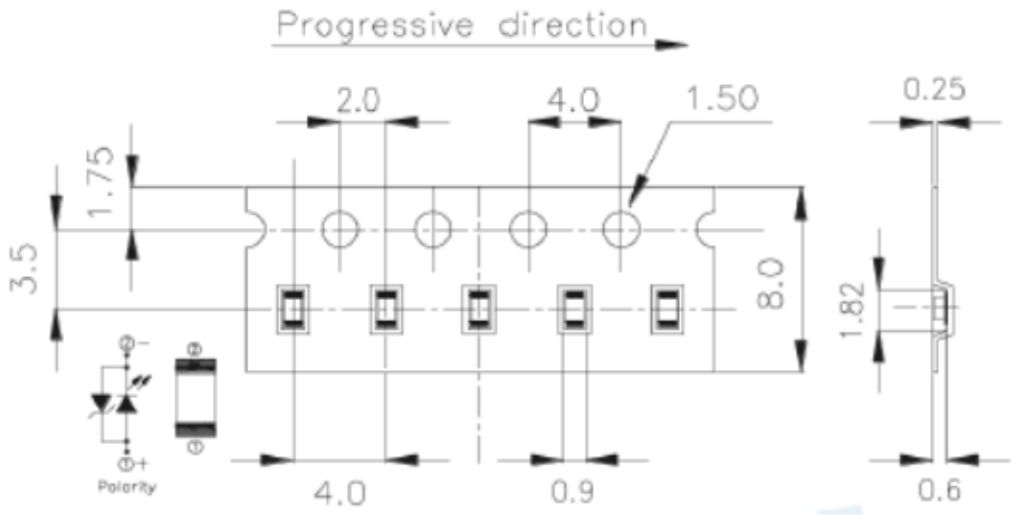
Note:

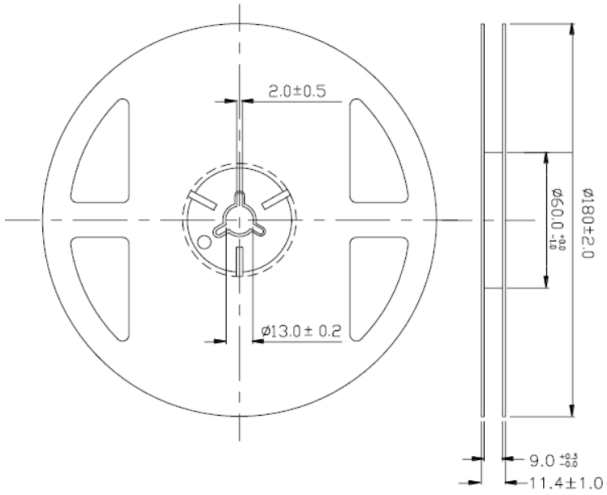
1. Recommend reflow temperature 240°C. The maximum soldering temperature should be limited to 260°C.
2. Maximum reflow soldering: 2 times.
3. Before, during, and after soldering, should not apply stress on the components and PCB board.

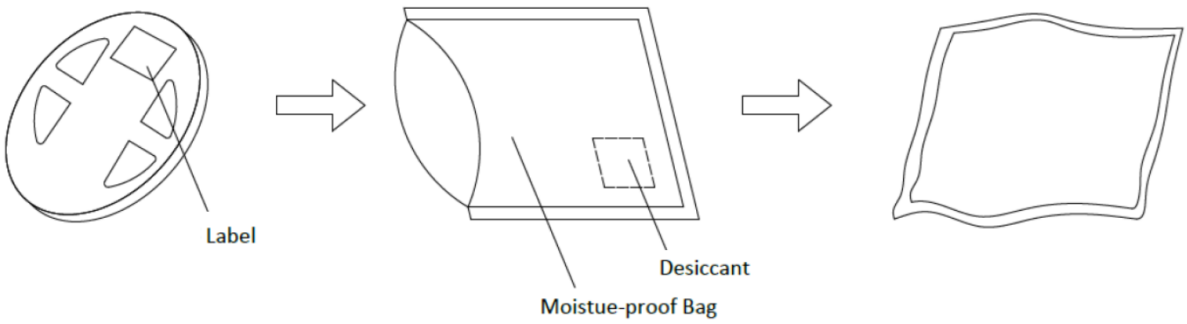
PACKING SPECIFICATION:

Reel Dimension:

Max.4000pcs/reel







PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

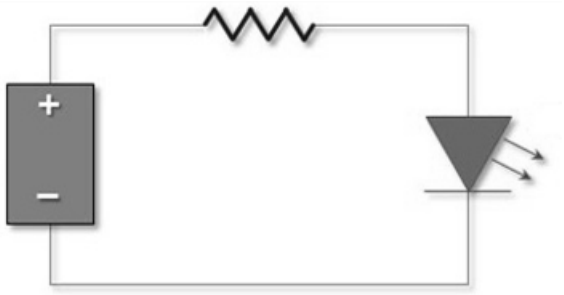
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 60±5°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

REVISION RECORD:

Version	Date	Summary of Revision
A1.0	09/01/2025	Datasheet set-up.